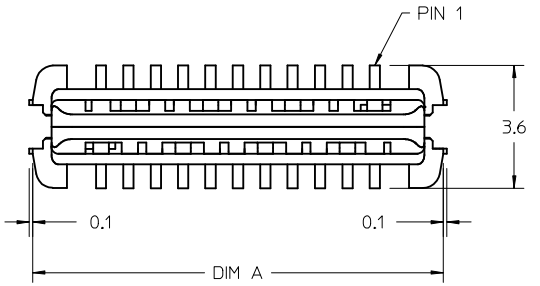
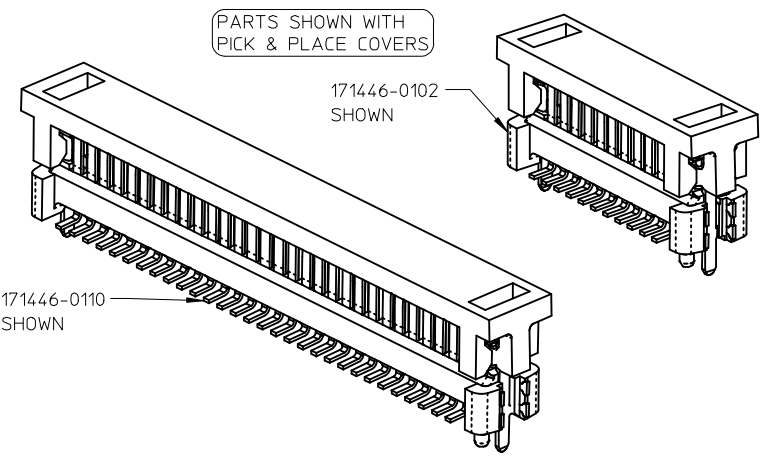
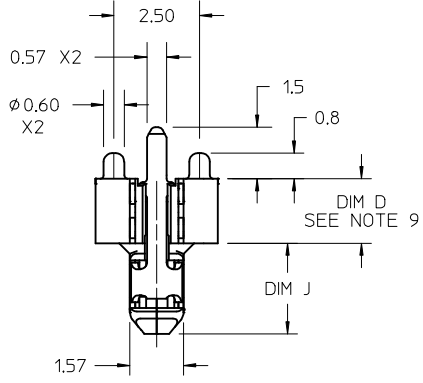
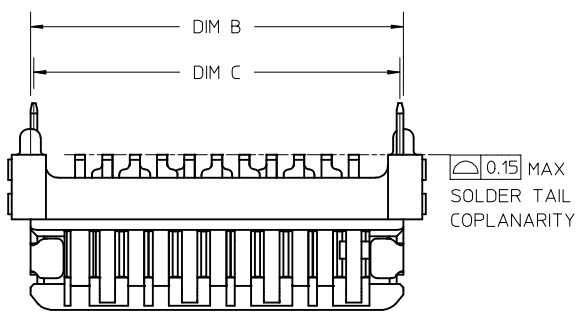


10 9 8 7 6 5 4 3 2 1



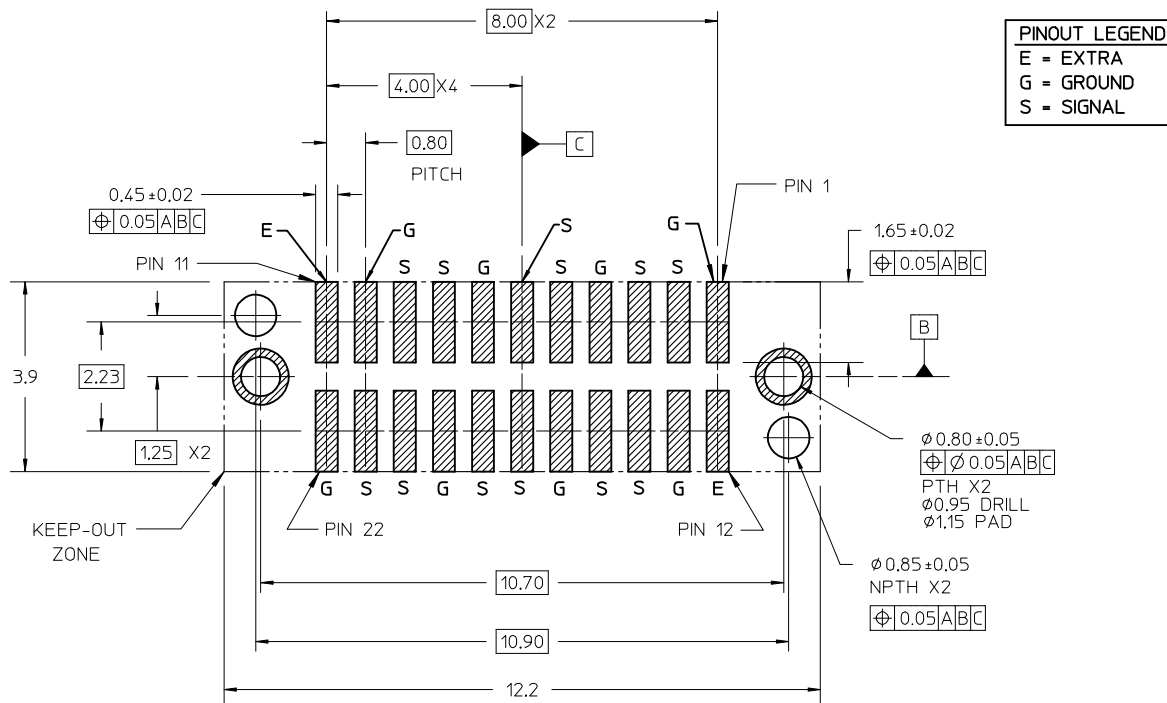
- NOTES:
1. MATERIALS: HOUSING: LCP, UL94V-0, BLACK
CONTACTS: HIGH PERFORMANCE COPPER ALLOY
 2. FINISH: 0.76 μ m MIN SELECT GOLD IN CONTACT AREA
SELECT TIN IN TAIL AREA, OVERALL NICKEL
 3. PRODUCT SPECIFICATION: PS-171446-0001
 4. PACKAGING SPECIFICATION: TAPE AND REEL
PER PK-70873-6003
 5. MATES WITH SPEEDSTACK RECEPTACLE: 171450
 6. APPLICATION SPECIFICATION: AS-171450-9998
 7. COSMETIC SPECIFICATION: PS-45499-002 CLASS B
 8. PART STATUS: CONTACT MOLEX
 9. DIM D ON THIS DRAWING PLUS DIM D ON DRAWING
SD-171450-0000 EQUALS THE SYSTEM MATED
STACK HEIGHT
 10. PARTS TO BE SHIPPED WITH PICK & PLACE COVERS.

PART NUMBER	CKT SIZE	DIFF PAIRS	SPARE CKTS	DIM A	DIM B	DIM C	DIM D	DIM J
171446-0101	22	6	2	12.0	10.90	10.70	0.90	2.6
171446-0102							1.90	
171446-0103							2.90	
171446-0104							3.90	3.6
171446-0105							0.90	
171446-0106							1.90	
171446-0107							2.90	
171446-0108							3.90	2.6
171446-0109							0.90	
171446-0110	1.90							
171446-0111	60	16	8	27.2	26.10	25.90	2.90	3.6
171446-0112							3.90	
171446-0113							0.90	
171446-0114							1.90	
171446-0115							2.90	
171446-0116							3.90	

REVISED EC NO: UCP2014-4032 DRWN: JBINGHAM 2014/03/27 CHKD: RNELSON 2014/03/27 APPR: JLAURX 2014/05/09 REV DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 7:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.13 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± ---	DRAWN BY DATE TGREGORI 2013/03/27 CHECKED BY DATE	TITLE PLUG ASSEMBLY SPEEDSTACK CONNECTOR		
		ANGULAR ± 1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPROVED BY DATE JCOMERC I 2013/04/25 MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-171446-0000		
			SIZE B	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
				SHEET NO. 1 OF 3		

9 8 7 6 5 4 3 2 1

PCB LAYOUT - 22 CKT



PINOUT LEGEND	
E	= EXTRA
G	= GROUND
S	= SIGNAL

PCB LAYOUT (COMPONENT SIDE)

SOLDER PASTE THICKNESS: 0.15 MIN
 DATUM **A** IS THE BOTTOM SURFACE OF THE PCB

NOTE:
 PIN NUMBERING IS FOR REFERENCE ONLY.
 OTHER PIN NUMBERS WILL NOT AFFECT THE
 OPERATION OF THE CONNECTOR.

SEE SHEET 1 EC NO: UCP2014-4032 DRAWN: IBINGHAM 2014/03/27 CHKD: RNELSON 2014/03/27 APPR: JLAURX 2014/05/09	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	REV DESCRIPTION	4 PLACES	mm INCH	DRAWN BY DATE TGREGORI 2013/03/27	TITLE PLUG ASSEMBLY SPEEDSTACK CONNECTOR		
		3 PLACES	± --- ± ---	CHECKED BY DATE			
		2 PLACES	± 0.13 ± ---	APPROVED BY DATE JCOMERC I 2013/04/25	molex DOCUMENT NO. SD-171446-0000 SHEET NO. 2 OF 3		
		1 PLACE	± 0.25 ± ---	MATERIAL NO.			
0 PLACE	± --- ± ---	ANGULAR ± 1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE B	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

